



YEA SHIN TECHNOLOGY CO., LTD

YS60N04AP

N-Channel Enhancement MOSFET

VDS= 60V, ID= 55A

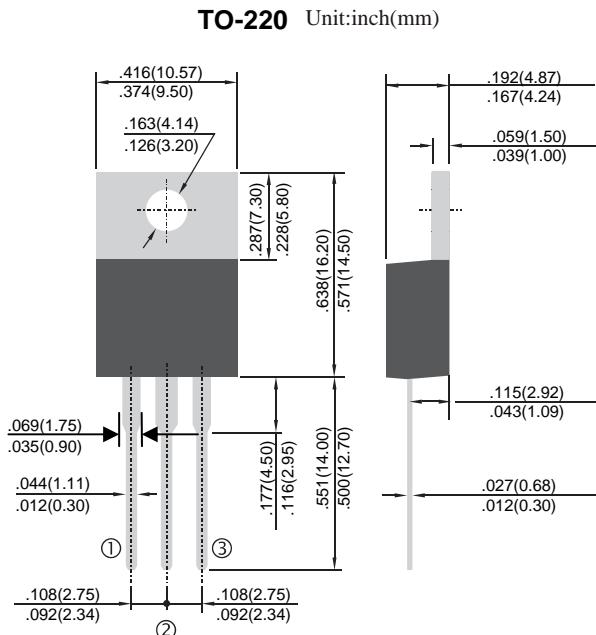
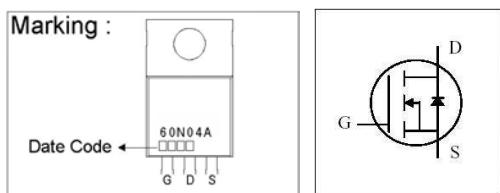
Description

The YS60N04AP is using trench DMOS technology. This advanced technology has been especially tailored to minimize $R_{DS(ON)}$, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

The YS60N04AP meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Feature

- Low On-Resistance
- Improve dv/dt Capability
- Green Device Available
- Fast switching
- 100% EAS Guaranteed



Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	$I_D @ T_C=25^\circ\text{C}$	55	A
	$I_D @ T_C=100^\circ\text{C}$	35	A
Pulsed Drain Current ^{1,2}	I_{DM}	220	A
Total Power Dissipation ⁴	$P_D @ T_C=25^\circ\text{C}$	96	W
	$P_D @ T_A=25^\circ\text{C}$	2	W
Single Pulse Avalanche Energy, $L=0.1\text{mH}^3$	E_{AS}	61	mJ
Single Pulse Avalanche Current, $L=0.1\text{mH}^3$	I_{AS}	35	A
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 ~ +150	°C

Thermal Data

Parameter	Symbol	Conditions	Max. Value	Unit
Thermal Resistance Junction-ambient ¹	$R_{\theta JA}$	Steady State	62.5	°C/W
Thermal Resistance Junction-case ¹	$R_{\theta JC}$	Steady State	1.3	°C/W

DEVICE CHARACTERISTICS

YS60N04AP

Electrical Characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	60	-	-	V	$\text{V}_{\text{GS}}=0$, $\text{I}_D=250\mu\text{A}$
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	1.2	1.6	2.5	V	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}$, $\text{I}_D=250\mu\text{A}$
Forward Transconductance	g_{fs}	-	11.5	-	S	$\text{V}_{\text{DS}}=10\text{V}$, $\text{I}_D=6\text{A}$
Gate-Source Leakage Current	I_{GSS}	-	-	± 100	nA	$\text{V}_{\text{GS}}= \pm 20\text{V}$
Drain-Source Leakage Current($T_j=25^\circ\text{C}$)	I_{DSS}	-	-	1	μA	$\text{V}_{\text{DS}}=60\text{V}$, $\text{V}_{\text{GS}}=0$
Drain-Source Leakage Current($T_j=125^\circ\text{C}$)		-	-	10	μA	$\text{V}_{\text{DS}}=48\text{V}$, $\text{V}_{\text{GS}}=0$
Static Drain-Source On-Resistance	$\text{R}_{\text{DS}(\text{ON})}$	-	10.5	12	$\text{m}\Omega$	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=30\text{A}$
		-	12	15		$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=15\text{A}$
Total Gate Charge ²	Q_g	-	39.2	-	nC	$\text{I}_D=10\text{A}$ $\text{V}_{\text{DS}}=30\text{V}$ $\text{V}_{\text{GS}}=10\text{V}$
Gate-Source Charge	Q_{gs}	-	5.9	-		
Gate-Drain ("Miller") Change	Q_{gd}	-	8.8	-		
Turn-on Delay Time ²	$\text{T}_{\text{d}(\text{on})}$	-	9.6	-	ns	$\text{V}_{\text{DS}}=15\text{V}$ $\text{I}_D=1\text{A}$ $\text{V}_{\text{GS}}=10\text{V}$ $\text{R}_G=6\Omega$
Rise Time	T_r	-	28.2	-		
Turn-off Delay Time	$\text{T}_{\text{d}(\text{off})}$	-	45.3	-		
Fall Time	T_f	-	10.9	-		
Input Capacitance	C_{iss}	-	2100	-	pF	$\text{V}_{\text{GS}}=0\text{V}$ $\text{V}_{\text{DS}}=25\text{V}$ $f=1.0\text{MHz}$
Output Capacitance	C_{oss}	-	165	-		
Reverse Transfer Capacitance	C_{rss}	-	80	-		
Gate Resistance	R_g	-	1.6	3.2	Ω	$f=1.0\text{MHz}$

Guaranteed Avalanche Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Single Pulse Avalanche Energy ⁵	EAS	33.8	-	-	mJ	$\text{V}_{\text{DD}}=25\text{V}$, $\text{L}=0.1\text{mH}$, $\text{I}_{\text{AS}}=26\text{A}$

Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Diode Forward Voltage ²	V_{SD}	-	-	1.2	V	$\text{I}_S=30\text{A}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_j=25^\circ\text{C}$
Continuous Source Current ^{1,6}	I_S	-	-	55	A	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current
Pulsed Source Current ^{2,6}	I_{SM}	-	-	220	A	

Notes: 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2. The data tested by pulsed, pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
3. The EAS data shows Max. rating. The test condition is $\text{VDD}=25\text{V}$, $\text{VGS}=10\text{V}$, $\text{L}=0.1\text{mH}$, $\text{IAS}=35\text{A}$.
4. The power dissipation is limited by 150°C junction temperature.
5. The Min. value is 100% EAS tested guarantee.
6. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

DEVICE CHARACTERISTICS

YS60N04AP

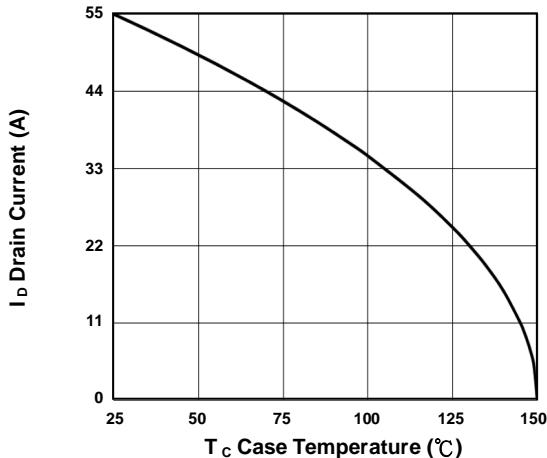


Fig.1 Drain Current vs. T_C

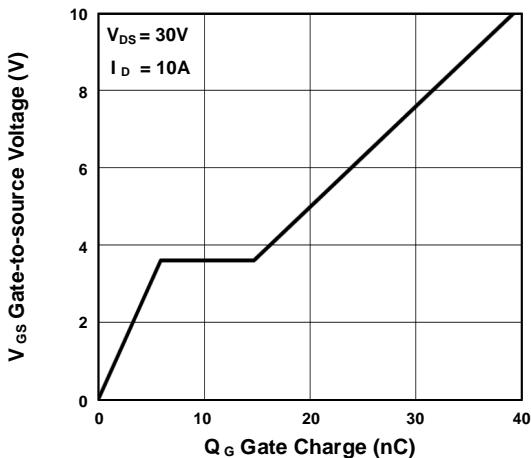


Fig.2 Gate Charge Characteristics

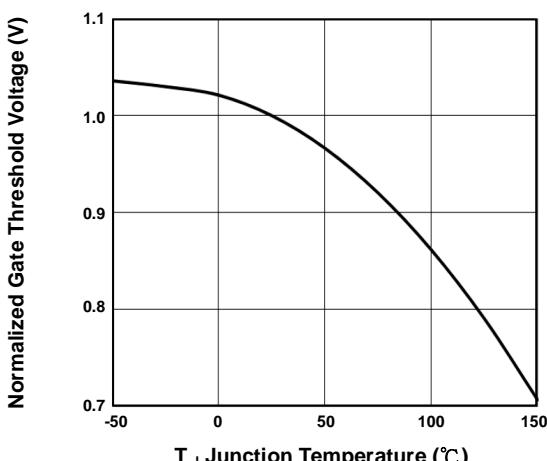


Fig.3 Normalized V_{GS(th)} vs. T_J

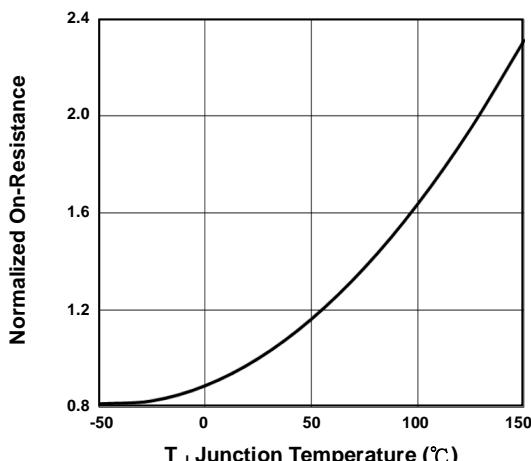


Fig.4 Normalized R_{DS(on)} vs. T_J

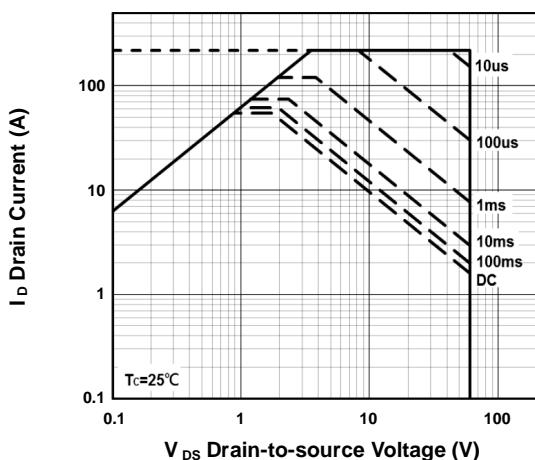


Fig.5 Safe Operating Area

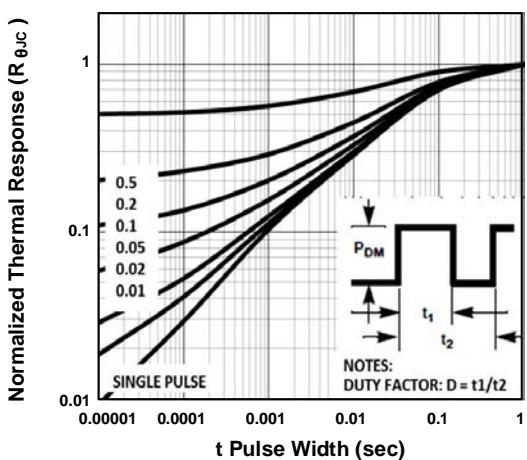


Fig.6 Transient Thermal Impedance

DEVICE CHARACTERISTICS

YS60N04AP

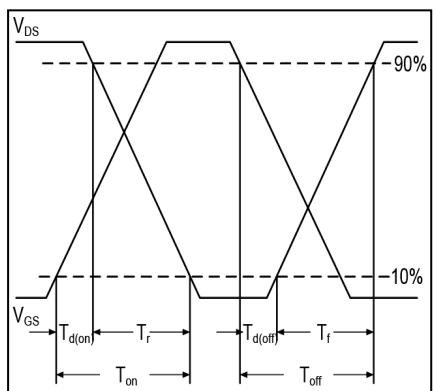


Fig.7 Switching Time Waveform

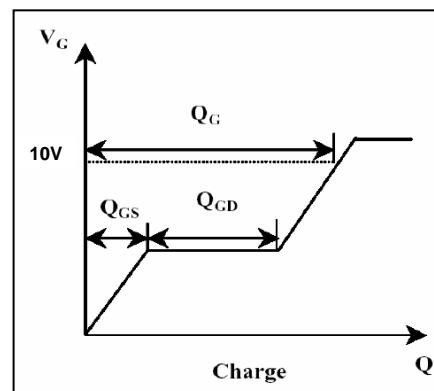


Fig.8 Gate Charge Waveform